

**Reply under 37 CFR 1.116
Expedited Procedure
Technology Center 2800**

LISTING OF THE CLAIMS

The following listing of claims is included for convenience purposes only. No new amendments are included herein.

Claims 1-19 (Canceled)

20. (Previously presented) A nitride based heterostructure device comprising:

a substrate;

a buffer layer on the substrate, wherein the buffer layer includes In; and

a quaternary layer on the buffer layer, wherein the quaternary layer includes Ga, Al, N, and In.

21. (Previously presented) The device of claim 20, wherein the substrate comprises one of the group comprising sapphire, SiC, ZnO, a spinel substrate, Si, anodized alumina, and AlN.

22. (Previously presented) The device of claim 20, wherein the quaternary layer includes about a 20% to 30% molar fraction of Al.

23. (Previously presented) The device of claim 22, wherein the quaternary layer further includes about a 2% to 5% molar fraction of In.

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24. (Previously presented) A nitride based heterostructure device comprising:

- a substrate;
- a buffer layer on the substrate, wherein the buffer layer includes In;
- a first layer including GaN on the buffer layer;
- a second layer on the first layer, wherein the second layer includes AlGa_N; and
- a quaternary layer on the second layer, wherein the quaternary layer includes AlInGa_N.

25. (Previously presented) The device of claim 24, wherein the substrate includes one of the group comprising sapphire, SiC, ZnO, a spinel substrate, Si, anodized alumina, and AlN.

26. (Previously presented) The device of claim 24, wherein the quaternary layer includes about a 20% to about 30% molar fraction of Al.

27. (Previously presented) The device of claim 26, wherein the quaternary layer further includes about a 2% to about 5% molar fraction of In.

28. (Previously presented) The device of claim 24, wherein the first layer further includes In.

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29. (Previously presented) A nitride based heterostructure device comprising:

a substrate;

a buffer layer on the substrate, wherein the buffer layer includes In;

a ternary layer on the buffer layer, wherein the ternary layer includes Ga, In, and N; and

a quaternary layer on the ternary layer, wherein the quaternary layer includes Ga, Al, In,
and N.

30. (Previously presented) The device of claim 29, wherein the buffer layer includes Al and N.